

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in circuits where high static and dynamic  $dV/dt$  and high  $dI/dt$  can occur. This "series BT" triac will commute the full RMS current at the maximum rated junction temperature ( $T_{j(max)} = 150\text{ °C}$ ) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by  $dV/dt$
- High junction operating temperature capability
- High voltage capability
- Least sensitive gate for highest noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

## 3. Applications

- Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- Motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

## 4. Quick reference data

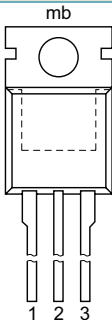
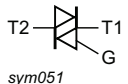
Table 1. Quick reference data

| Symbol       | Parameter                            | Conditions  | Min | Typ | Max | Unit |
|--------------|--------------------------------------|---|-----|-----|-----|------|
| $V_{DRM}$    | repetitive peak off-state voltage    |   | -   | -   | 800 | V    |
| $I_{T(RMS)}$ | RMS on-state current                 | full sine wave; $T_{mb} \leq 131\text{ °C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | -   | -   | 10  | A    |
| $I_{TSM}$    | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>  | -   | -   | 100 | A    |

| Symbol                  | Parameter                             | Conditions   |  | Min  | Typ | Max | Unit |
|-------------------------|---------------------------------------|--|--|------|-----|-----|------|
| Static characteristics  |                                       |  |  |      |     |     |      |
| I <sub>GT</sub>         | gate trigger current                  | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA   |
|                         |                                       | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA   |
|                         |                                       | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA   |
| Dynamic characteristics |                                       |  |  |      |     |     |      |
| dV <sub>D</sub> /dt     | rate of rise of off-state voltage     | V <sub>DM</sub> = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit                  |  | 1000 | -   | -   | V/μs |
| dI <sub>com</sub> /dt   | rate of change of commutating current | V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 10 A; dV <sub>com</sub> /dt = 20 V/μs; (snubberless condition); gate open circuit |  | 20   | -   | -   | A/ms |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                    | Simplified outline  | Graphic symbol  |
|-----|--------|--------------------------------|---|---|
| 1   | T1     | main terminal 1                |  |  |
| 2   | T2     | main terminal 2                |   |   |
| 3   | G      | gate                           |   |   |
| mb  | T2     | mounting base; main terminal 2 |   |   |

## 6. Ordering information

Table 3. Ordering information

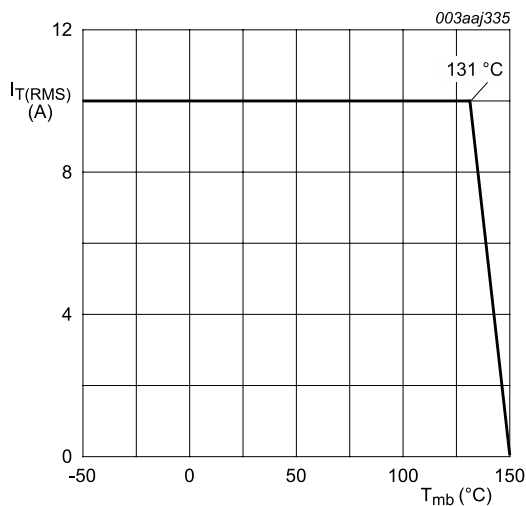
| Type number  | Package  |  |         |
|--------------|----------|--|---------|
|              | Name     | Description  | Version |
| BTA410-800BT | TO-220AB | plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB | SOT78   |

## 7. Limiting values

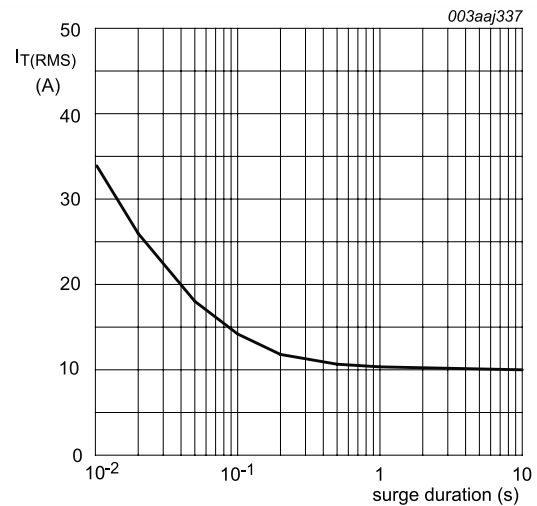
**Table 4. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol              | Parameter                            | Conditions   | Min | Max | Unit                   |
|---------------------|--------------------------------------|--|-----|-----|------------------------|
| $V_{\text{DRM}}$    | repetitive peak off-state voltage    |  | -   | 800 | V                      |
| $I_{\text{T(RMS)}}$ | RMS on-state current                 | full sine wave; $T_{\text{mb}} \leq 131\text{ }^{\circ}\text{C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>         | -   | 10  | A                      |
| $I_{\text{TSM}}$    | non-repetitive peak on-state current | full sine wave; $T_{\text{J(init)}} = 25\text{ }^{\circ}\text{C}$ ; $t_{\text{p}} = 20\text{ ms}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | -   | 100 | A                      |
|                     |                                      | full sine wave; $T_{\text{J(init)}} = 25\text{ }^{\circ}\text{C}$ ; $t_{\text{p}} = 16.7\text{ ms}$  | -   | 110 | A                      |
| $I^2t$              | $I^2t$ for fusing                    | $t_{\text{p}} = 10\text{ms}$ ; sine-wave pulse   | -   | 50  | $\text{A}^2\text{s}$   |
| $dI_{\text{T}}/dt$  | rate of rise of on-state current     | $I_{\text{G}} = 100\text{ mA}$   | -   | 100 | $\text{A}/\mu\text{s}$ |
| $I_{\text{GM}}$     | peak gate current                    |  | -   | 2   | A                      |
| $P_{\text{GM}}$     | peak gate power                      |  | -   | 5   | W                      |
| $P_{\text{G(AV)}}$  | average gate power                   | over any 20 ms period  | -   | 0.5 | W                      |
| $T_{\text{stg}}$    | storage temperature                  |  | -40 | 150 | $^{\circ}\text{C}$     |
| $T_{\text{j}}$      | junction temperature                 |  | -   | 150 | $^{\circ}\text{C}$     |



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



**Fig. 2. RMS on-state current as a function of surge duration; maximum values**  
 $f = 50\text{Hz}$ ;  $T_{\text{mb}} = 131\text{ }^{\circ}\text{C}$

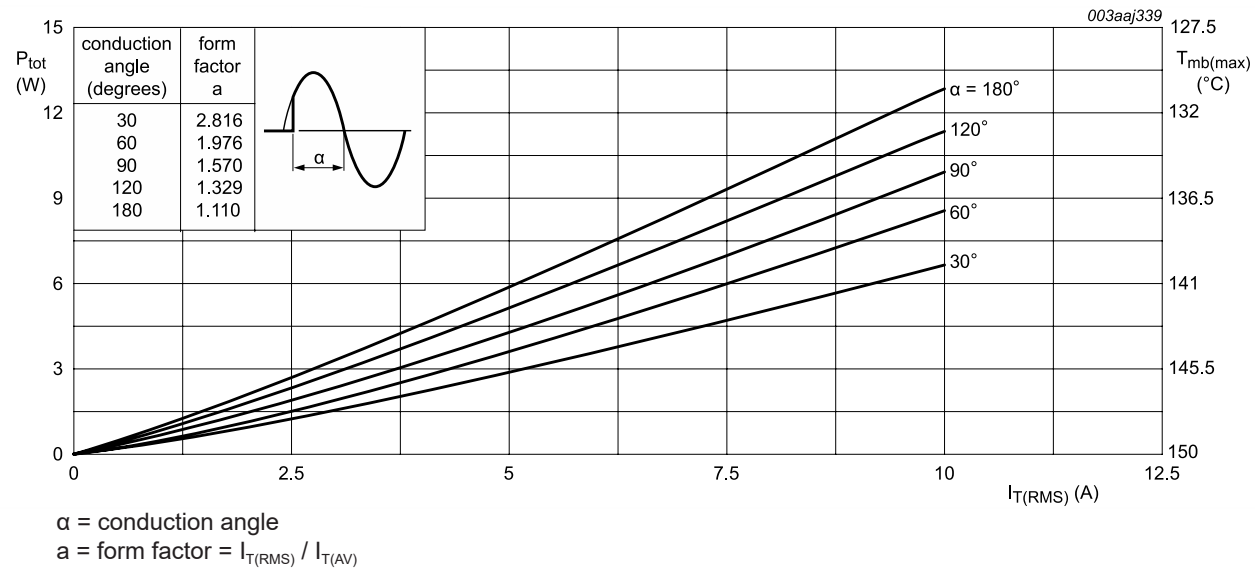


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

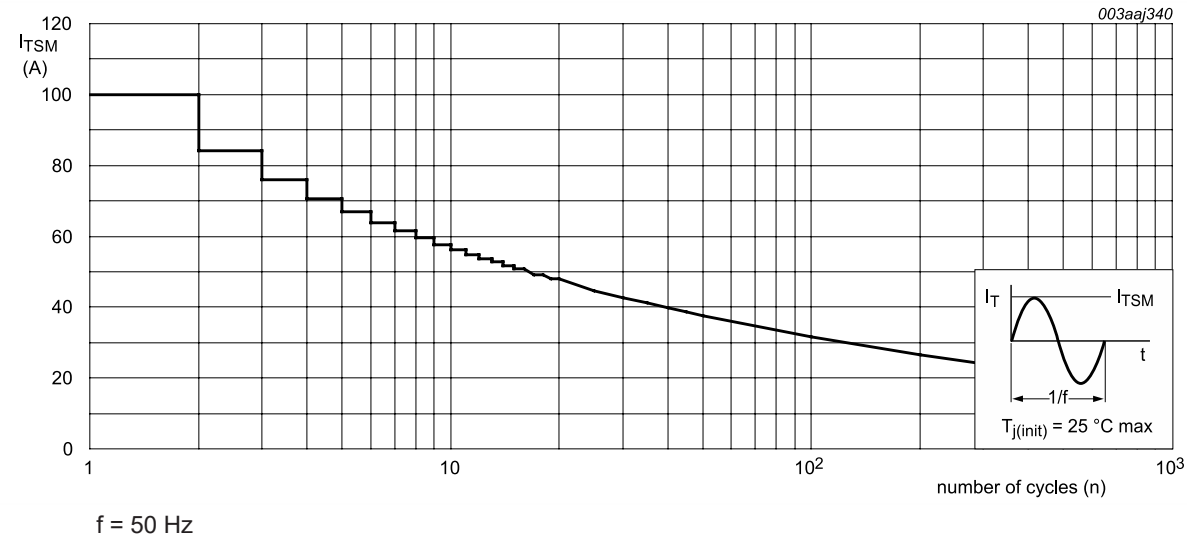


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

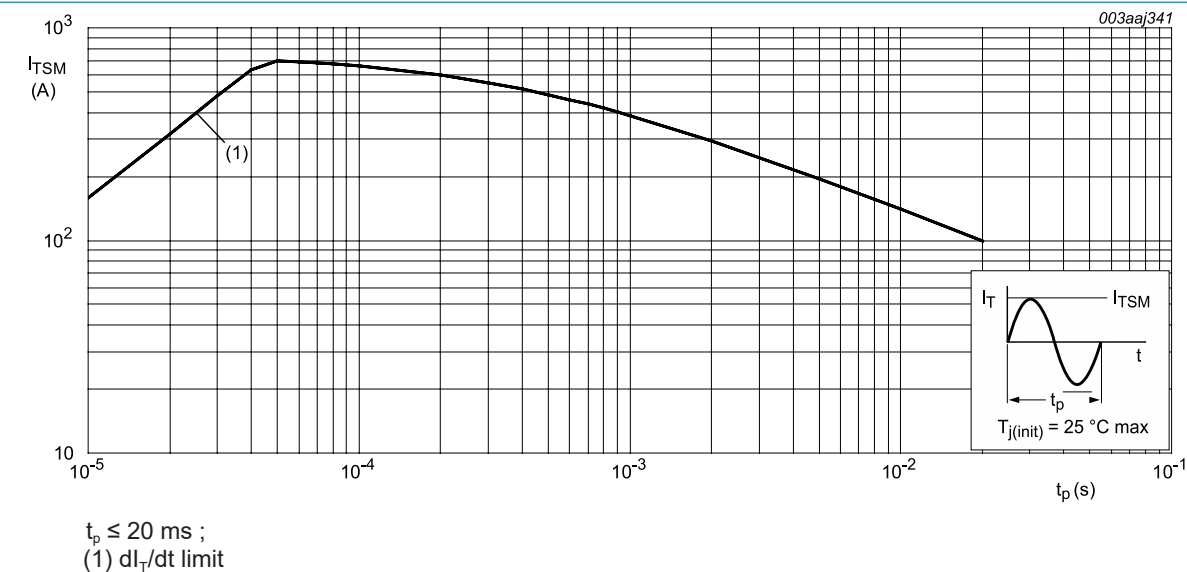
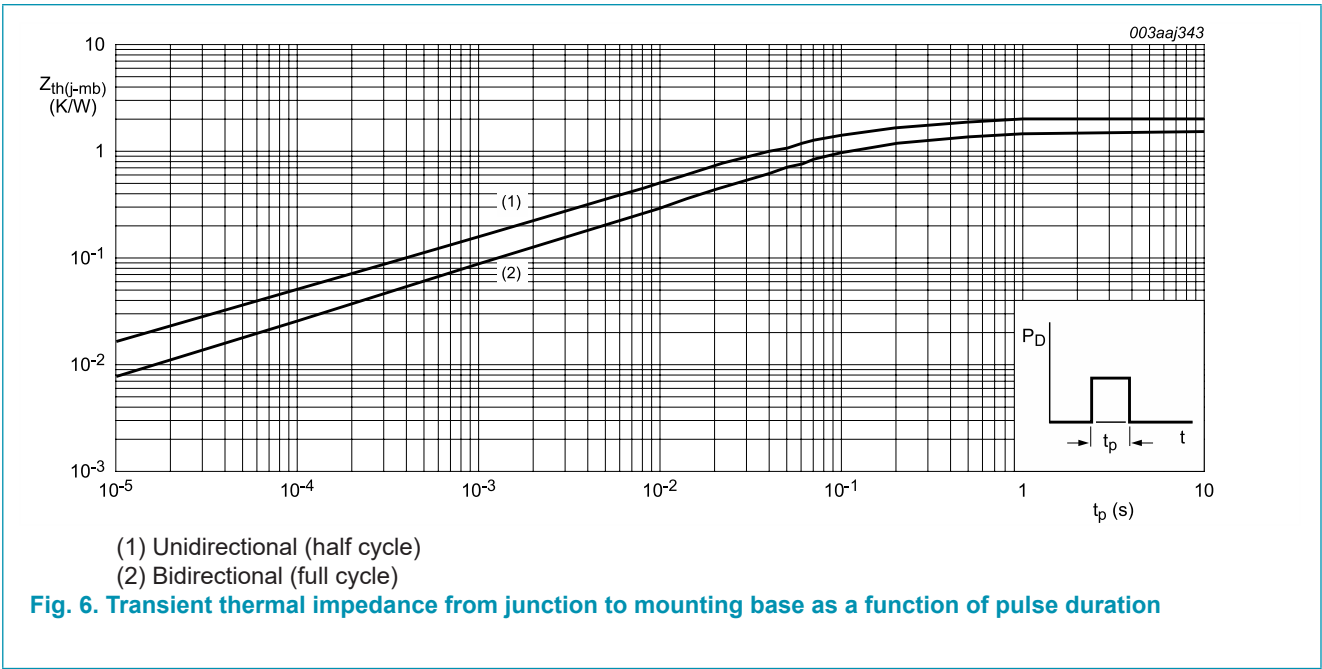


Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

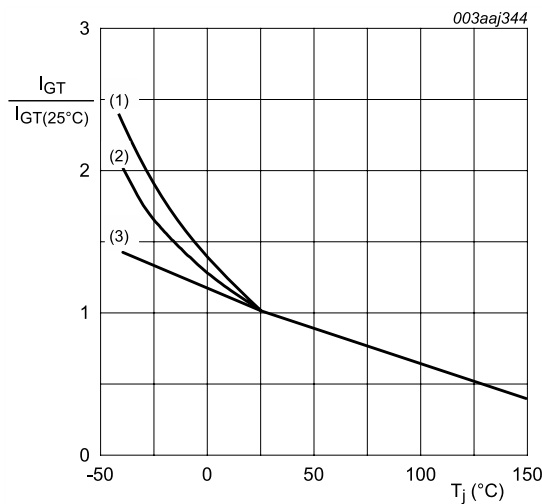
| Symbol         | Parameter   | Conditions         |  | Min | Typ | Max | Unit |
|----------------|---|--------------------|--|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | full cycle; Fig. 6 |  | -   | -   | 1.5 | K/W  |
|                |   | half cycle; Fig. 6 |  | -   | -   | 2   | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       | in free air        |  | -   | 60  | -   | K/W  |



## 9. Characteristics

Table 6. Characteristics

| Symbol                         | Parameter                             | Conditions   |  | Min  | Typ | Max | Unit             |
|--------------------------------|---------------------------------------|--|--|------|-----|-----|------------------|
| <b>Static characteristics</b>  |                                       |  |  |      |     |     |                  |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>  |  | 2    | -   | 50  | mA               |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  |  | -    | -   | 60  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  |  | -    | -   | 90  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-;<br>$T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>  |  | -    | -   | 60  | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>  |  | -    | -   | 60  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 15\text{ A}$ ; $T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>   |  | -    | 1.3 | 1.6 | V                |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}$ ; $T_J = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 11</a>   |  | -    | 0.8 | 1   | V                |
|                                |                                       | $V_D = 400\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$ ; <a href="#">Fig. 11</a>   |  | 0.25 | 0.4 | -   | V                |
| $I_D$                          | off-state current                     | $V_D = 800\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$   |  | -    | 0.4 | 2   | mA               |
| <b>Dynamic characteristics</b> |                                       |  |  |      |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 536\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                                      |  | 1000 | -   | -   | V/ $\mu\text{s}$ |
| $dI_{com}/dt$                  | rate of change of commutating current | $V_D = 400\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 20\text{ V}/\mu\text{s}$ ; (snubberless condition); gate open circuit |  | 20   | -   | -   | A/ms             |
|                                |                                       | $V_D = 400\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 10\text{ V}/\mu\text{s}$ ; gate open circuit                          |  | 28   | -   | -   | A/ms             |
|                                |                                       | $V_D = 400\text{ V}$ ; $T_J = 150\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 10\text{ A}$ ; $dV_{com}/dt = 1\text{ V}/\mu\text{s}$ ; gate open circuit                           |  | 45   | -   | -   | A/ms             |



- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

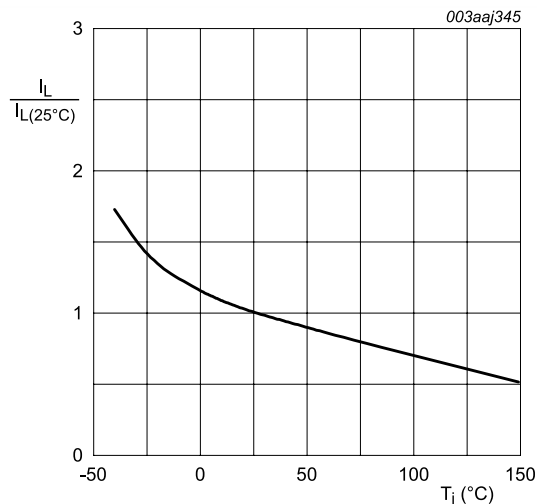


Fig. 8. Normalized latching current as a function of junction temperature

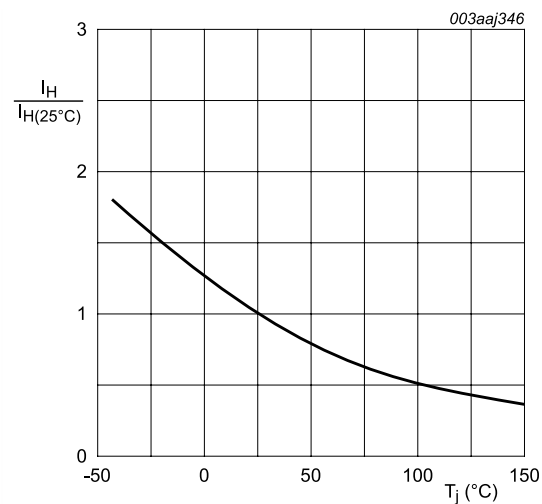
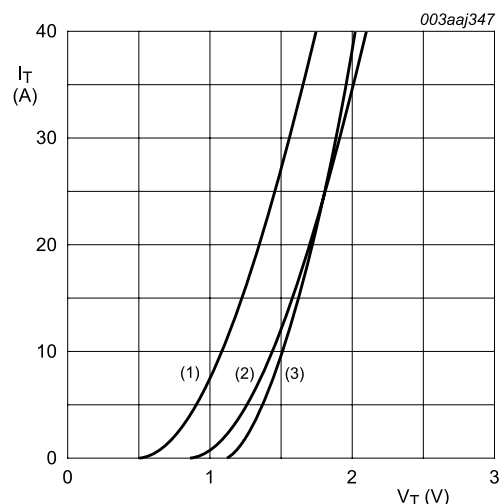


Fig. 9. Normalized holding current as a function of junction temperature



- $V_o = 1.142 \text{ V}$ ;  $R_s = 0.027 \text{ }\Omega$
- (1)  $T_J = 150^{\circ}\text{C}$ ; typical values
  - (2)  $T_J = 150^{\circ}\text{C}$ ; maximum values
  - (3)  $T_J = 25^{\circ}\text{C}$ ; maximum values

Fig. 10. On-state current as a function of on-state voltage

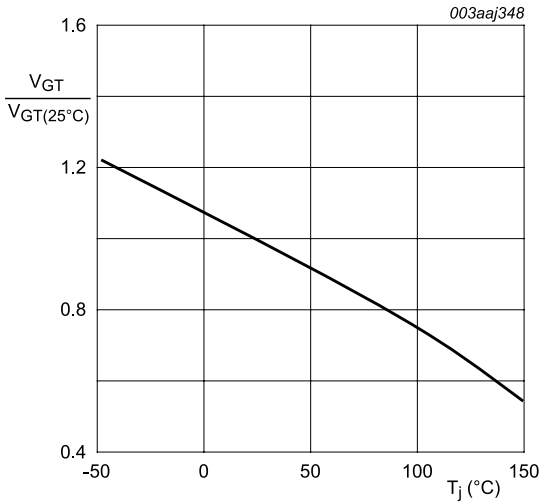
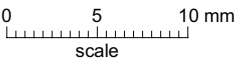
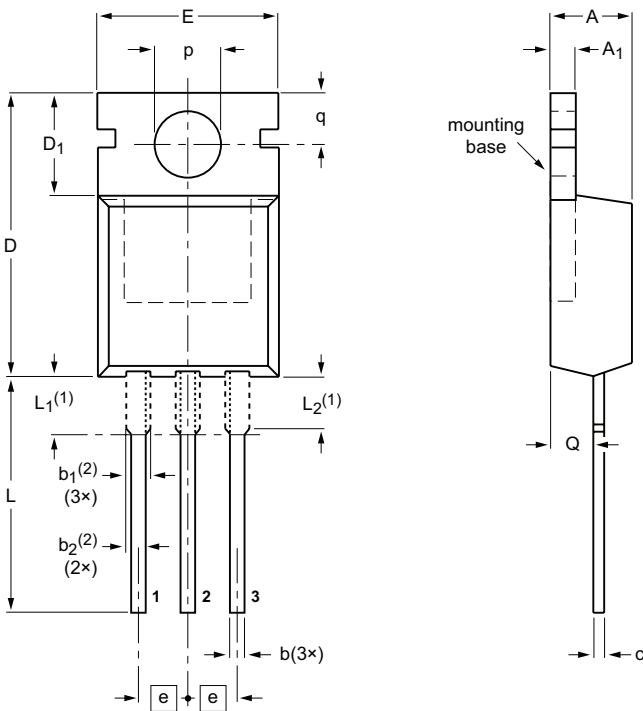


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



10. Package outline


Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB SOT78



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub> | b          | b <sub>1</sub> <sup>(2)</sup> | b <sub>2</sub> <sup>(2)</sup> | c          | D            | D <sub>1</sub> | E           | e    | L            | L <sub>1</sub> <sup>(1)</sup> | L <sub>2</sub> <sup>(1)</sup><br>max. | p          | q          | Q          |
|------|------------|----------------|------------|-------------------------------|-------------------------------|------------|--------------|----------------|-------------|------|--------------|-------------------------------|---------------------------------------|------------|------------|------------|
| mm   | 4.7<br>4.1 | 1.40<br>1.25   | 0.9<br>0.6 | 1.6<br>1.0                    | 1.3<br>1.0                    | 0.7<br>0.4 | 16.0<br>15.2 | 6.6<br>5.9     | 10.3<br>9.7 | 2.54 | 15.0<br>12.8 | 3.30<br>2.79                  | 3.0                                   | 3.8<br>3.5 | 3.0<br>2.7 | 2.6<br>2.2 |

- Notes
- Lead shoulder designs may vary.
  - Dimension includes excess dambar.

| OUTLINE<br>VERSION | REFERENCES |                 |       |  | EUROPEAN<br>PROJECTION  | ISSUE DATE           |
|--------------------|------------|-----------------|-------|--|---|----------------------|
|                    | IEC        | JEDEC           | JEITA |  |   |                      |
| SOT78              |            | 3-lead TO-220AB | SC-46 |  |  | 08-04-23<br>08-06-13 |

## 11. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.ween-semi.com>.

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Date of release: 10 August 2018



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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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